

SMP3030-01ETG TVS Arrays

Description

The SMP3030 includes low capacitance rail to rail diodes with an additional Zener diode to provide protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes above the maximum level specified in the IEC61000-4-2 international standard ($\pm 20\text{kV}$ contact discharge) without performance degradation. The low loading capacitance makes it ideal for protecting high speed data lines such as HDMI, DVI, USB2.0, USB3.0 and eSATA.

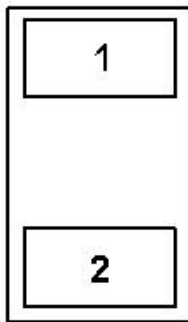
Features

- ESD protection in accordance with:
IEC 61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 20\text{kV}$ (contact)
IEC 61000-4-5 (lightning) 3A (8/20 μs)
IEC 61000-4-4 (EFT) 40A (5/50ns)
- Low capacitance of 0.5pF @ $V_R=0\text{V}$
- Low leakage current of 0.1 μA at 5V
- Small SOD882 packaging helps save board space

Applications

- Tablets
- Ultrabook
- eReader
- Smart Phones
- Digital Cameras
- MP3/ PMP
- Set Top Boxes
- Portable Medical

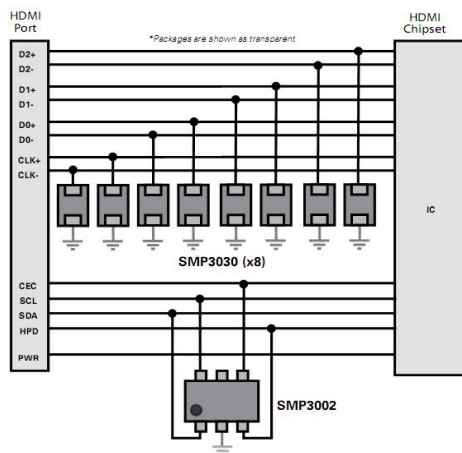
Pinout



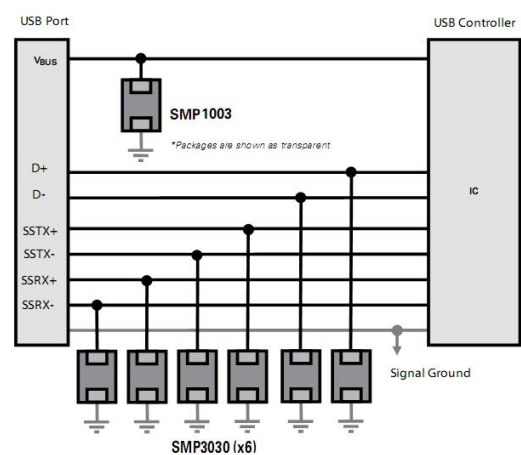
Functional Block Diagram



HDMI Application Example



USB3.0 Application Example



Ordering Information

Device	Package	Packaging Options	P0/P1	Packaging Specifications	Min. Order Qty.
SMP3030-01ETG	SOD882	Tape & Reel - 8mm tape/7" reel	4mm/2mm	EIA-481	10000

Absolute Maximum Ratings @T_A=25°C unless otherwise specified

Parameter	Symbol	Value	Units
Peak Pulse Current (tp=8/20µs)	I _{PP}	3.0	A
Operating Temperature	T _{OP}	-40 to + 125	°C
Storage Temperature	T _{STOR}	-55 to + 150	°C

CAUTION: Stresses above those listed in “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

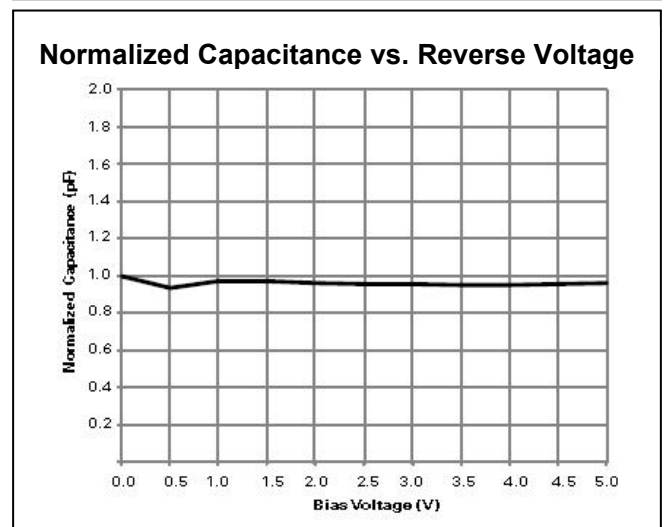
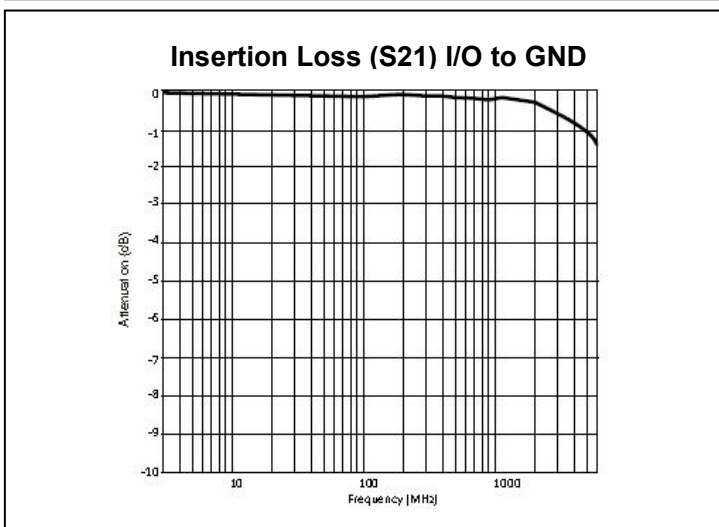
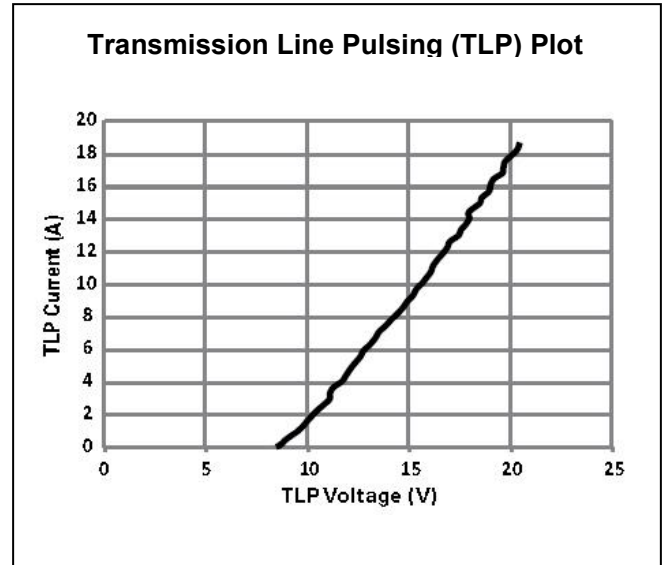
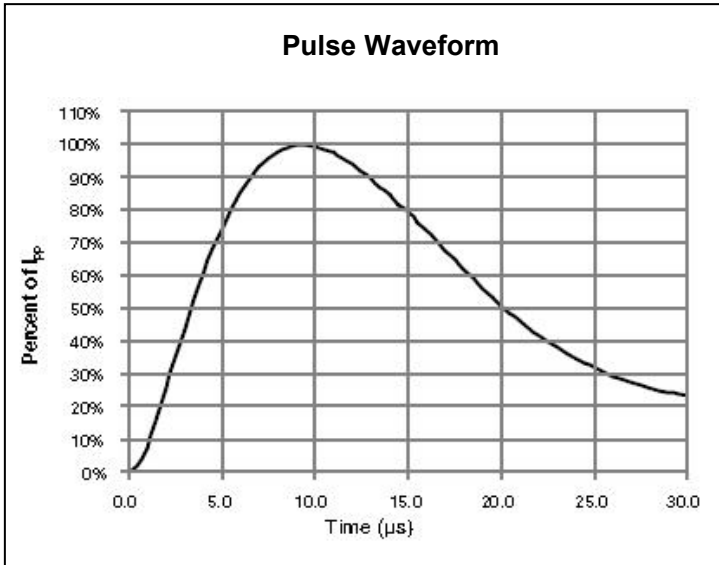
Parameter	Value	Units
Storage Temperature Range	-55 to + 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

Electrical Characteristics (T_{OP}=25°C)

Characteristics	Symbol	Condition	Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V _{RWM}	-	-	-	5	V
Reverse Leakage Current	I _{LEAK}	V _R =5V with 1pin at GND	-	0.1	0.5	µA
Clamping Voltage ¹	V _C	I _{PP} = 1A, tp=8/20µs, Fwd	-	9.2	-	V
		I _{PP} = 2A, tp=8/20µs, Fwd	-	10.0	-	V
ESD With stand Voltage ¹	V _{ESD}	IEC61000-4-2 (Contact)	± 20	-	-	kV
		IEC61000-4-2 (Air)	± 30	-	-	kV
Dynamic Resistance	R _{DYN}	(V _{C2} -V _{C1})/(I _{PP2} -I _{PP1})	-	0.55	-	Ω
Junction Capacitance ¹	C _J	Reverse Bias=0V, f=1 MHz	-	0.5	-	pF

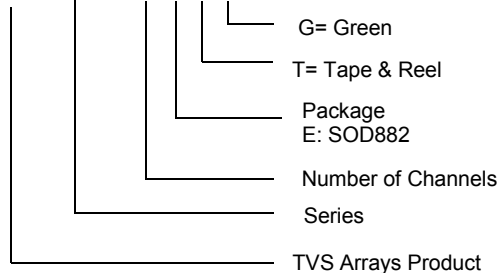
Note: 1. Parameter is guaranteed by design and/or device characterization.

Ratings and Characteristics Curves



Part Name Information

SMP 3030 - 01 E T G



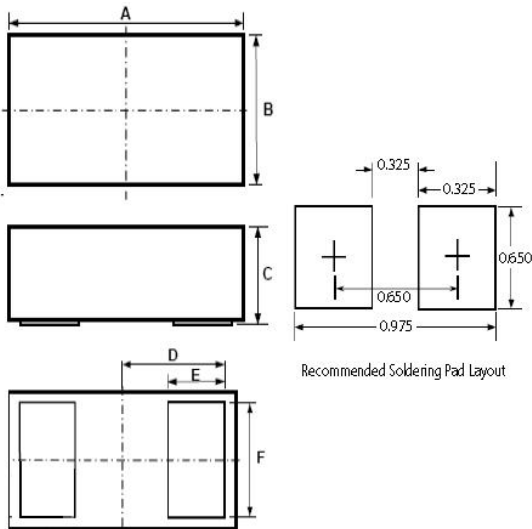
Marking Diagram



Where X is SMP3030-01ETG

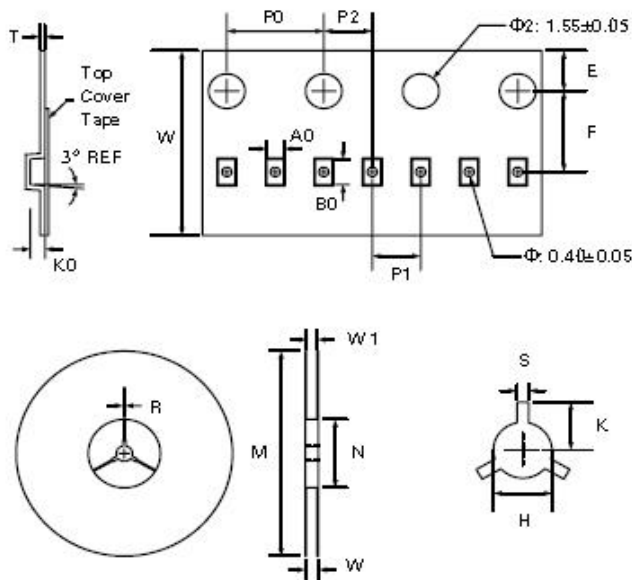
X = Product ID "T" or "W"

Mechanical Dimensions SOD882



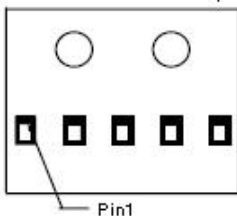
Symbol	Package			SOD882		
	JEDEC			MO-236		
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.90	1.00	1.10	0.037	0.039	0.041
B	0.50	0.60	0.70	0.022	0.024	0.026
C	0.40	0.50	0.60	0.016	0.020	0.024
D	0.45			0.018		
E	0.20	0.25	0.35	0.008	0.010	0.012
F	0.45	0.50	0.55	0.018	0.020	0.022

Embossed Carrier Tape & Reel Specification — SOD882



Symbol	Tape Dimensions	
	Millimeters	
	Min	Max
A0	0.65	0.75
B0	1.10	1.20
K0	0.50	0.60
E	1.65	1.85
F	3.45	3.55
P0	3.90	4.10
P1	1.90	2.10
P2	1.95	2.05
T	1.95	2.05
W	7.90	8.10

Device Orientation in Tape



Symbol	Reel Dimensions (Size ϕ 178)	
	Millimeters	
	Min	Max
M	177.0	179.0
N	59.0	61.0
W	11.0	12.0
W1	8.5	9.5
H	12.5	13.5
S	1.9	2.1
K	10.8	11.2
R	0.95	1.05

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